

Insulated-Gate Bipolar Transistor in a TO-3P Plastic Package.

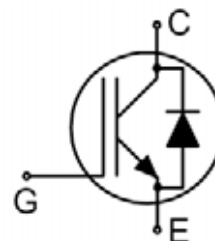
### Features

Low gate charge,, Low saturation voltage ,  
Positive temperature coefficient, RoHS product.

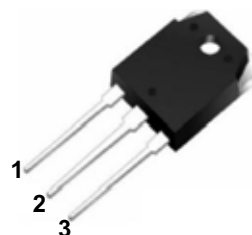
### Applications

General purpose inverter, Frequency converters,  
Induction Heating(IH), Uninterrupted Power Supply(UPS).

### Equivalent Circuit



### Pinning



PIN1 : Gate  
PIN 2 : Collector  
PIN 3 : Emitter

### Absolute Maximum Ratings(Ta=25°C)

| Parameter  | Symbol         | Rating  | Unit |
|--|----------------|---------|------|
| Collector-emitter voltage                              | $V_{CES}$      | 1200    | V    |
| Gate-emitter voltage                                   | $V_{GES}$      | ±20     | V    |
| Collector current                                      | $I_C$          | 50      | A    |
| Collector current@ $T_C=100^\circ\text{C}$             |                | 25      | A    |
| Collector peak current,<br>$T_P$ limited by $T_{JMAX}$ | $I_{CM}$       | 60      | A    |
| Diode forward current@ $T_C=100^\circ\text{C}$         | $I_F$          | 25      | A    |
| Diode maximum forward current                          | $I_{FM}$       | 75      | A    |
| Power dissipation( $T_C=25^\circ\text{C}$ )            | $P_D$          | 350     | W    |
| Operating junction and storage temperature range       | $T_J, T_{stg}$ | -55~150 | °C   |
| Maximum temperature for soldering                      | $T_L$          | 300     | °C   |
| IGBT thermal resistance,junction-case                  | $R_{th(j-c)}$  | 0.4     | °C/W |
| Diode thermal resistance,junction-case                 | $R_{th(j-C)}$  | 2       | °C/W |
| Thermal resistance,junction-ambient                    | $R_{th(j-a)}$  | 40      | °C/W |

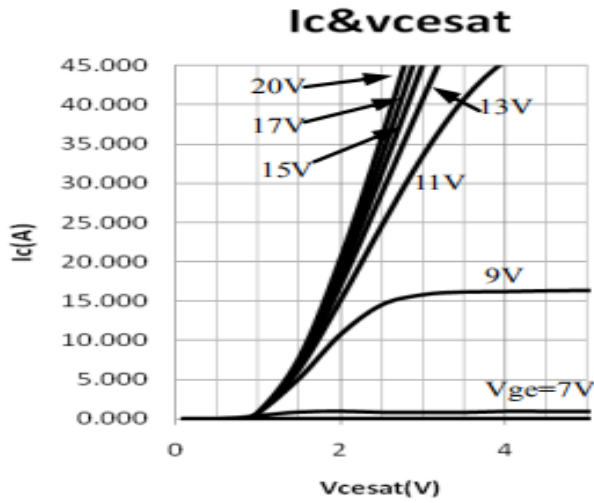
**Electrical Characteristics(Ta=25°C)**

| Parameter                                 | Symbol                               | Test Conditions  | Min  | Typ  | Max       | Unit |
|---|--------------------------------------|--|------|------|-----------|------|
| Collector-emitter breakdown voltage       | $V_{CES}$                            | $V_{GE}=0V$ $I_{CE}=250\mu A$                                  | 1200 | -    | -         | V    |
| Breakdown Voltage Temperature Coefficient | $\frac{\Delta BV_{CES}}{\Delta T_J}$ | $I_{CE}=1mA$ ;reference to 25°C                                |      | 0.6  |           | V/°C |
| Zero gate voltage Collector current       | $I_{CES}$                            | $V_{GE}=0V;V_{CE}=1200V$<br>$T_C=25^\circ C$                   | -    | -    | 0.2       | mA   |
|   |                                      | $T_C=100^\circ C$  |      |      | 2         | mA   |
|   |                                      | $T_C=150^\circ C$  |      |      | 2.5       | mA   |
| Gate-body leakage current                 | $I_{GES}$                            | $V_{GE}=\pm 20V$ $V_{CE}=0V$                                   | -    | -    | $\pm 100$ | nA   |
| Gate threshold voltage                    | $V_{GE(th)}$                         | $I_C=600\mu A$ $V_{CE}=V_{GE}$                                 | 4.5  | -    | 6.5       | V    |
| Collector-emitter saturation voltage      | $V_{CE(sat)}$                        | $I_C=25A; V_{GE}=15V$<br>$T_C=25^\circ C$                      | -    | 1.8  | 2.45      | V    |
|   |                                      | $T_C=100^\circ C$  |      | 2.0  |           | V    |
|   |                                      | $T_C=150^\circ C$  |      | 2.1  |           | V    |
| Short Collector current                   | $I_{C(SC)}$                          | $V_{GE}=15V;V_{CE}=600V;$<br>$t_{sc}<10\mu s$ $T_C=25^\circ C$ |      | 160  |           | A    |
| Input capacitance                         | $C_{ies}$                            | $V_{CE}=25V$ $V_{GE}=0V$<br>$f=1MHz$                           | -    | 1600 | 2400      | pF   |
| Output capacitance                        | $C_{oes}$                            |  | -    | 120  | 190       |      |
| Reverse transfer capacitance              | $C_{res}$                            |  | -    | 84   | 130       |      |

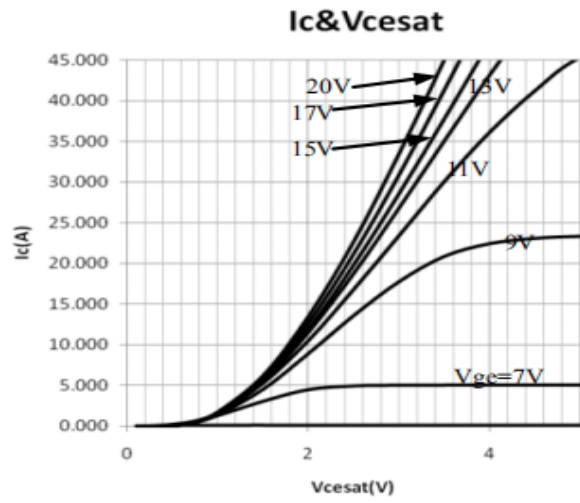
**Electrical Characteristics(Ta=25 °C)**

| Parameter               | Symbol       | Test Conditions   | Min | Typ  | Max | Unit |
|-------------------------|--------------|---|-----|------|-----|------|
| Turn-on delay time      | $t_{d(ON)}$  | $V_{CE}=600V$ $I_C=25A$<br>$R_G=10\Omega$<br>Inductive Load | -   | 90   | -   | ns   |
| Rise time               | $t_r$        |   | -   | 75   | -   |      |
| Turn-off delay time     | $t_{d(OFF)}$ |   | -   | 210  | -   |      |
| Fall time               | $t_f$        |   | -   | 100  | -   |      |
| Turn-On Switching Loss  | $E_{on}$     |   | -   | 2.8  | -   |      |
| Turn-Off Switching Loss | $E_{off}$    | -   | 1.1 | -    |     |      |
| Total Switching Loss    | $E_{ts}$     | -   | 3.9 | -    |     |      |
| Total gate charge       | $Q_G$        | $V_{CE}=600V$ $I_C=25A$<br>$V_{GE}=15V$                     | -   | 177  | 274 | nC   |
| Gate-emitter charge     | $Q_{G-E}$    |   | -   | 16   | 26  |      |
| Gate-collector charge   | $Q_{G-C}$    |   | -   | 61   | 94  |      |
| Diode forward voltage   | $V_F$        | $I_F=25A$   | -   | 1.7  | 2.9 | V    |
| Reverse recovery time   | $T_{rr}$     | $V_{GE}=0V,$ $V_R=800V$<br>$I_F=25A$                        | -   | 230  |     | ns   |
| Reverse recovery charge | $Q_{rr}$     | $di/dt=200A/\mu S$  | -   | 1200 |     | nC   |

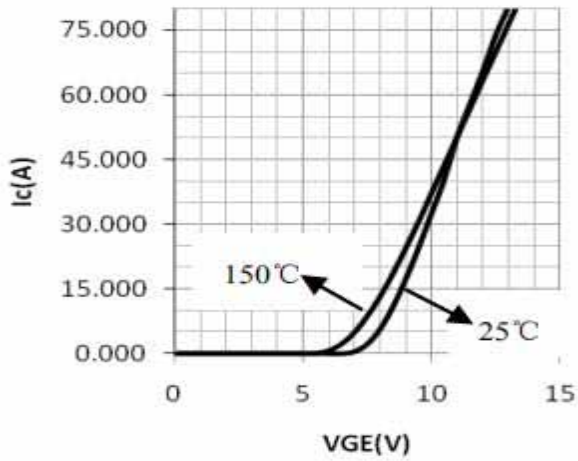
## RATING AND CHARACTERISTICS CURVES (RI25N1200TP)



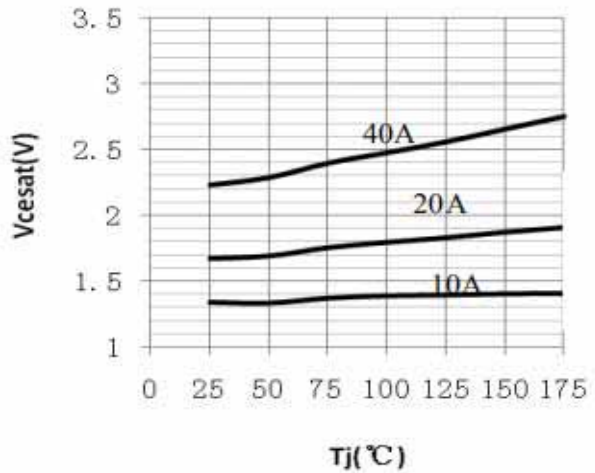
1. Typical Output Characteristics ( $T_j=25^\circ\text{C}$ )



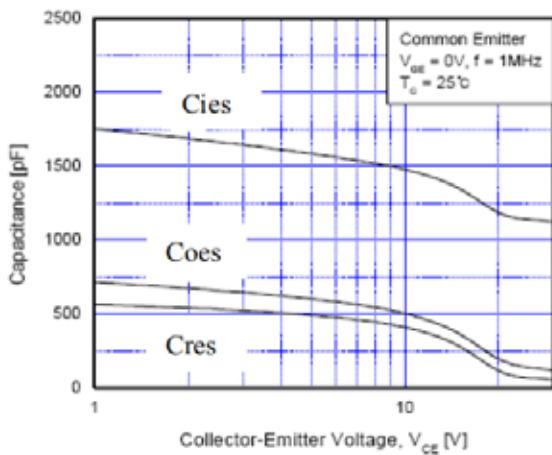
2. Typical Output Characteristics ( $T_j=150^\circ\text{C}$ )



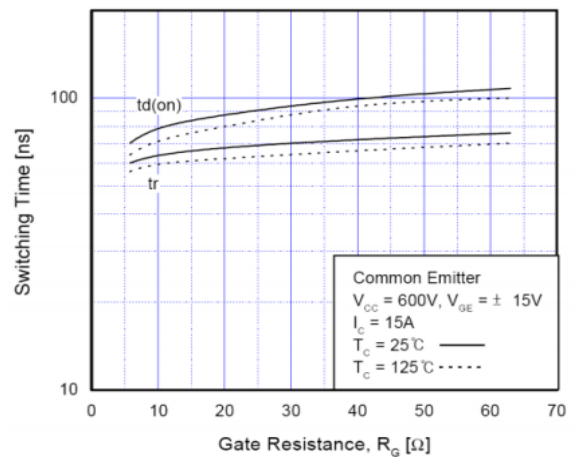
3. Typical Saturation Voltage Characteristics



4. Saturation Voltage vs. Case Temperature at Variant Current Level

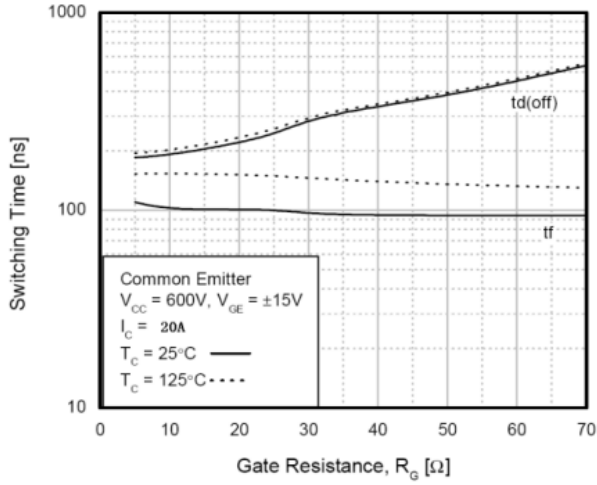


5. Capacitance Characteristics

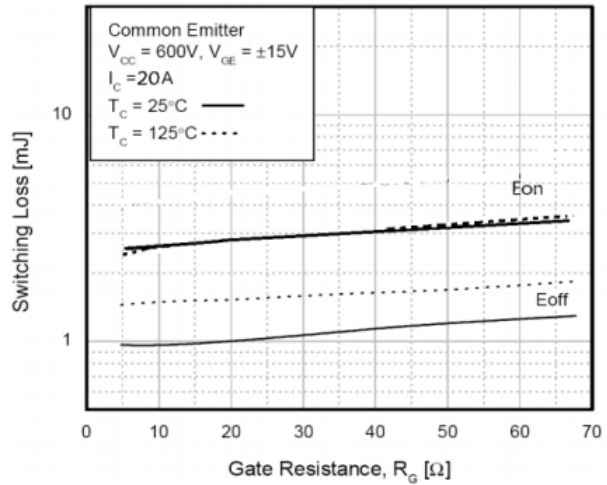


6. Turn-On Characteristics vs. Gate Resistance

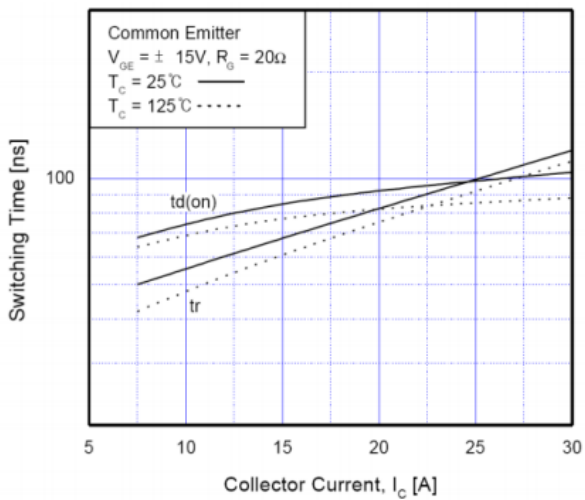
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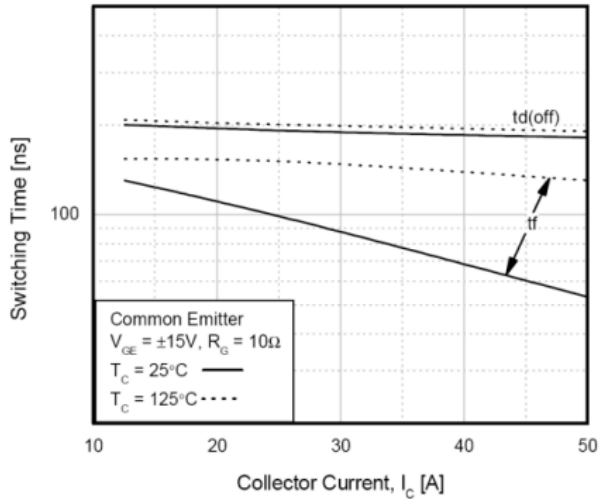
7. Turn-Off Characteristics vs. Gate Resistance



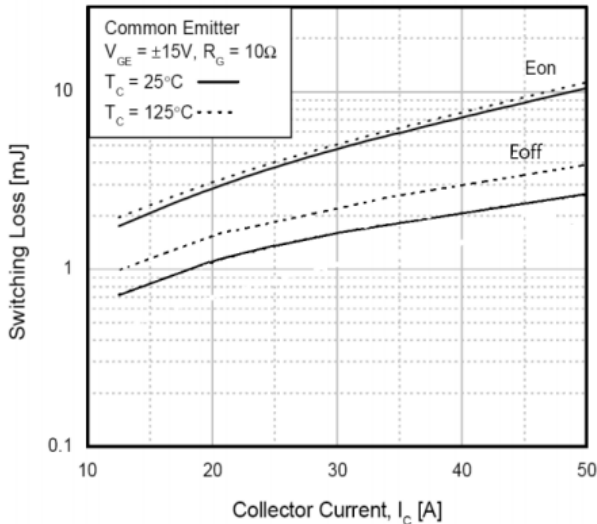
8. Switching Loss vs. Gate Resistance



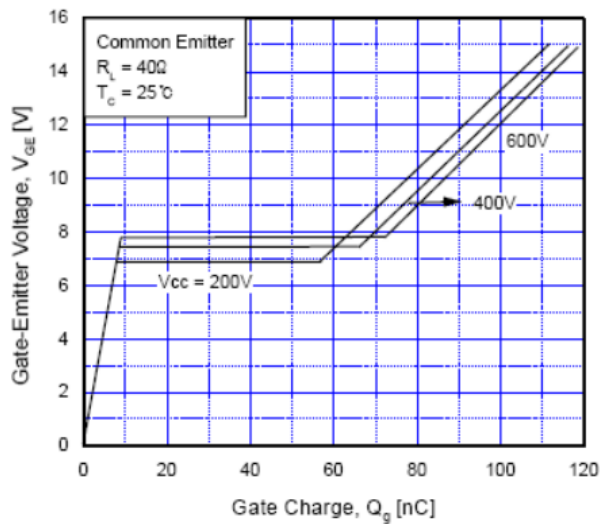
9. Turn-On Characteristics vs. Collector Current



10. Turn-Off Characteristics vs. Collector Current

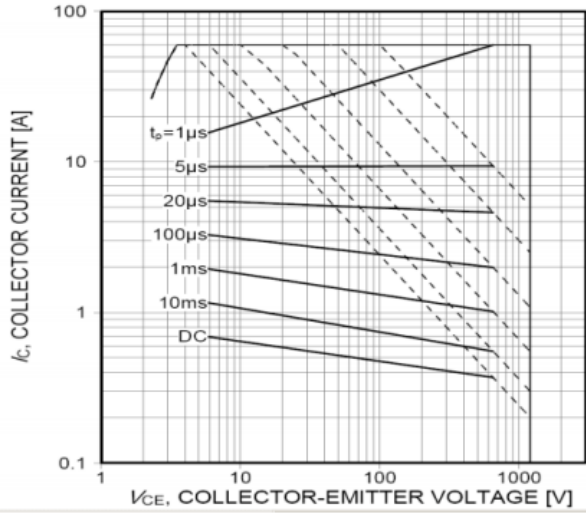


11. Switching Loss vs. Collector Current

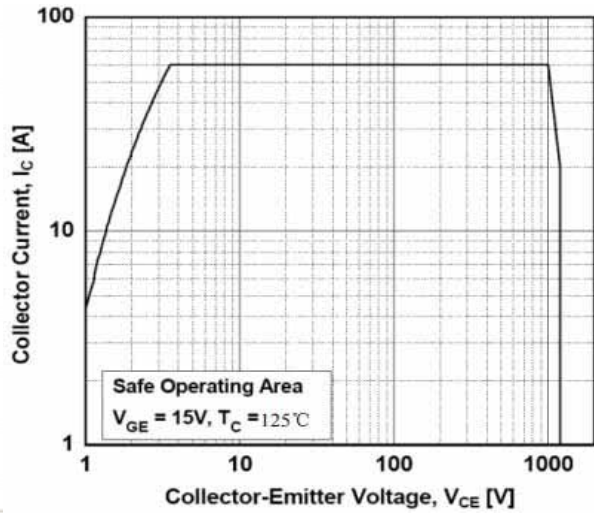


12. Gate Charge Characteristics

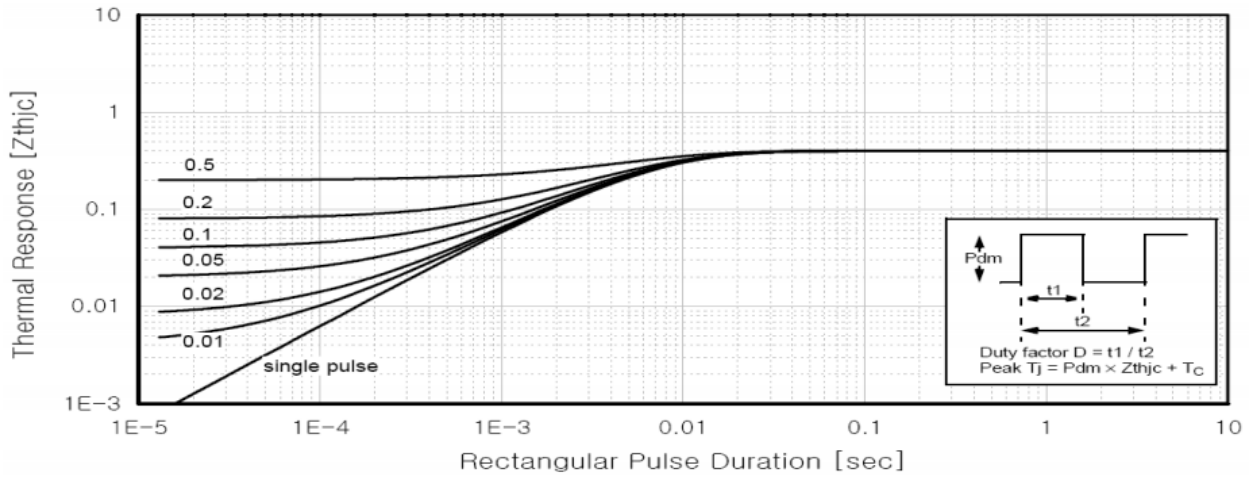
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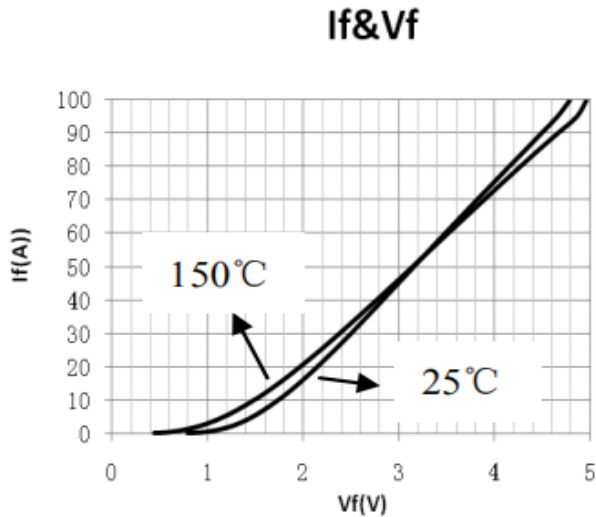
13.SOA Characteristics



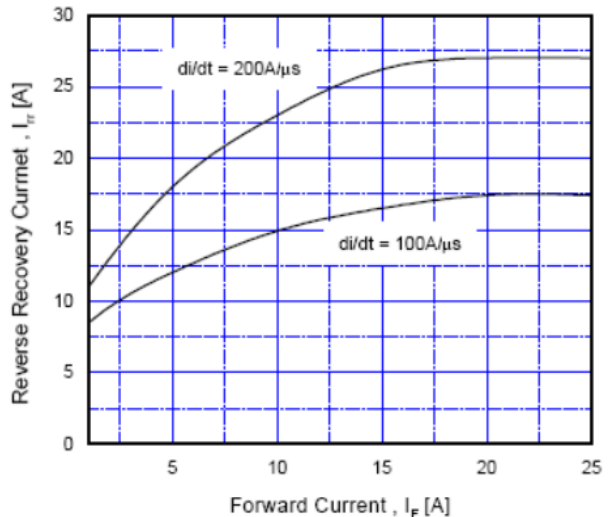
14.Turn-Off SOA



15.Transient Thermal Impedance

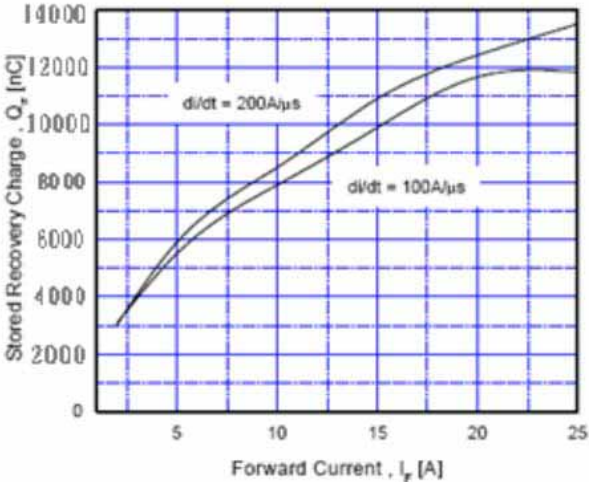


16.Forward Characteristics

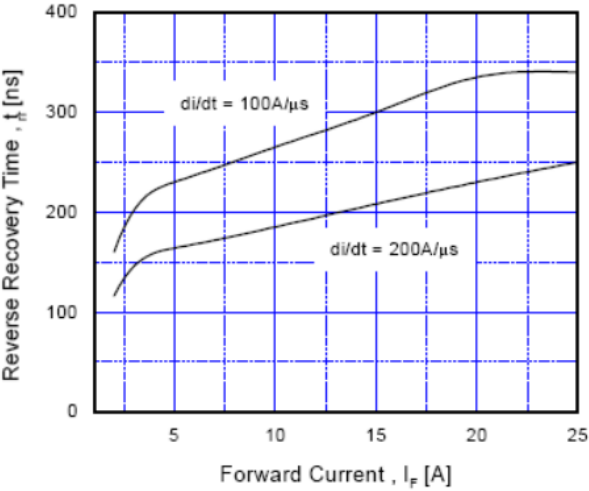


17.Reverse Recovery Current

# RATING AND CHARACTERISTICS CURVES (RI25N1200TP)



18. Stored Charge

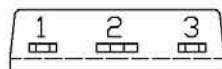
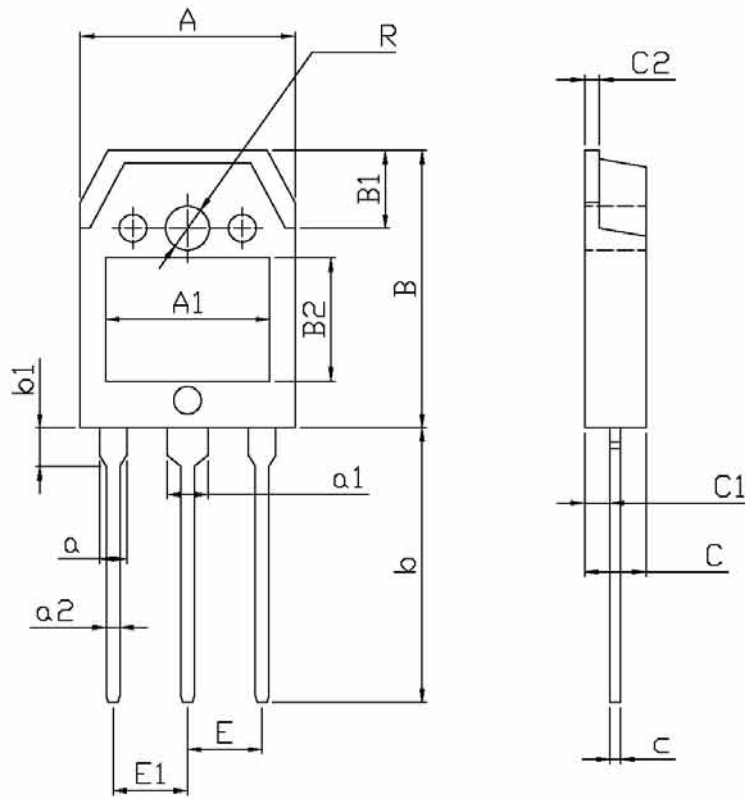


19. Reverse Recovery Time

Package Dimensions

T□-3P

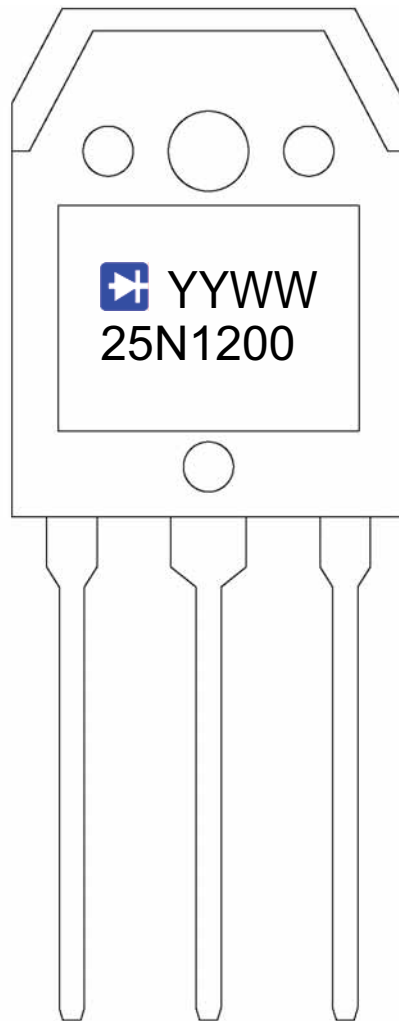
单位: mm



| Symbol | Dimensions In Millimeters |      | Symbol | Dimensions In Millimeters |     |
|--------|---------------------------|------|--------|---------------------------|-----|
|        | Min                       | Max  |        | Min                       | Max |
| A      | 15.4                      | 16.0 | a2     | 0.8                       | 1.2 |
| R      | 3.1                       | 3.5  | E      | 5.45                      |     |
| B      | 19.8                      | 20.8 | E1     | 5.45                      |     |
| B1     | 5.5                       | 5.9  | C      | 4.3                       | 4.7 |
| B2     | 9.0                       |      | C1     | 1.2                       | 1.6 |
| A1     | 12.0                      |      | C2     | 1.4                       | 1.6 |
| b      | 19.6                      | 20.6 | c      | 0.5                       | 0.7 |
| b1     | 3.0                       | 3.4  |        |                           |     |
| a      | 1.8                       | 2.2  |        |                           |     |
| a1     | 2.8                       | 3.2  |        |                           |     |



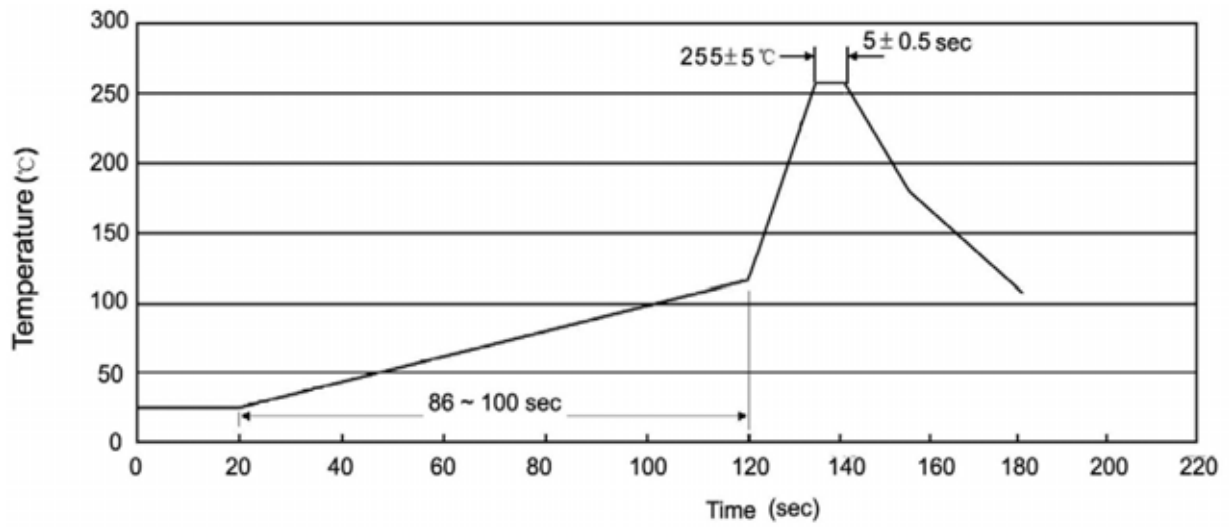
## Marking Instructions



Note:  
Logo+ YYWW: Date Code.  
25N1200(Product Type.)



**Temperature Profile for Dip Soldering(Pb-Free)**



N o t e :

- 1.Preheating:25~150 °C, Time:60~90sec.
- 2.PeakTemp.:255±5°C, Duration:5±0.5sec.
- 3.Cooling Speed: 2~10 °C/sec.

**Resistance to Soldering Heat Test Conditions**

Temp.:270±5 °C      Time:10±1 sec

**Packaging SPEC.**

T U B E

| Package Type | Units      |                 |                 |                       |                 | Dimension (unit: mm <sup>3</sup> ) |            |             |
|--------------|------------|-----------------|-----------------|-----------------------|-----------------|------------------------------------|------------|-------------|
|              | Units/Tube | Tubes/Inner Box | Units/Inner Box | Inner Boxes/Outer Box | Units/Outer Box | Tube                               | Inner Box  | Outer Box   |
| TO-3P        | 30         | 15              | 450             | 5                     | 2250            | 497.5×46×8                         | 555×164×50 | 575×290×180 |

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